



OLED SPECIFICATION

Model No:

REX012864GYPP3N00000

CUSTOMER:

APPROVED BY	
PCB VERSION	
DATE	

FOR CUSTOMER USE ONLY

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY
Release DATE:		100	



1. Revision History

VERSION	DATE	REVISED PAGE NO.	Note
0	2014/05/21		First release
Α	2014/05/30		Correct Low Level
			Output
В	2014/06/16		Add Low Temperature
			storage.
С	2015/01/16		Modify ICC
			Modify Brightness
D	2015/02/25		Modify Interface
E	2015/05/12		Correct Contour
			Drawing
F	2015/11/16		Modify Life Time
G	2016/06/01		Modify Static
			electricity test



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- 2. Module Classification Information
- 3.Interface Pin Function
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1.General Specification

The Features is described as follow:

■ Module dimension: 60.5 × 37.0 × 2.15 mm

■ Active area: 55.01 × 27.49mm

■ Dot Matrix: 128*64

Dot size: 0.40 × 0.40 mmDot pitch: 0.43 × 0.43 mm

■ Display Mode : Passive Matrix

■ Duty: 1/64 Duty

■ Display Color: OLED , Yellow

■ Controller IC: SSD1309Z



2.Module Coding System

1	2	3	4	5	6	7	8	9	10	11	12	13	14
R	Е	Х	012864	G	Υ	Р	Р	3	N	0	0	0	00

1	Brand : Raystar Opt	tronics Inc.						
2	E : OLED							
3	Display Type : C→C	Character, G→Graph	ic , T→TAB ,X→COG	, H→COG (with Frame)				
4	Dot Matrix: 128*64	4						
5	Series							
		A : Amber	R : Red	C : Full Color				
6	Emitting Color	B : Blue	W : White					
	Limiting Color	G : Green	Y : Yellow					
		S : Sky Blue	X : Dual Color					
7	Polarizer	P : With Polarizer;	N: Without Polarizer					
'	Polarizei	A : Anti-glare Pola	A : Anti-glare Polarizer					
8	Display Mode	P : Passive Matrix	P:Passive Matrix;N:Active Matrix					
9	Driver Voltage	3:3.0~3.3V; 5	5 : 5.0V					
10	Touch Panel	N : Without touch	panel; T: With touch pa	nel				
		0 : Standard						
		1 : Sunlight Readable						
11	Product type	2 : Transparent OLED (TOLED)						
		3 : Flexible OLED	(FOLED)					
		4 : OLED Lighting						
	1 /	0 : Standard						
12	Inchestion Crade	2 : B grade						
12	Inspection Grade	C : Automotive gra	ide					
		Y : Consumer grad	de					
13	Interface	0 : Default ; F : FF	PC;H:Hot bar;D:D	emo Kit				
14	Serial No.	Serial number(00~	ZZ)					
	•	*						







3.Interface Pin Function

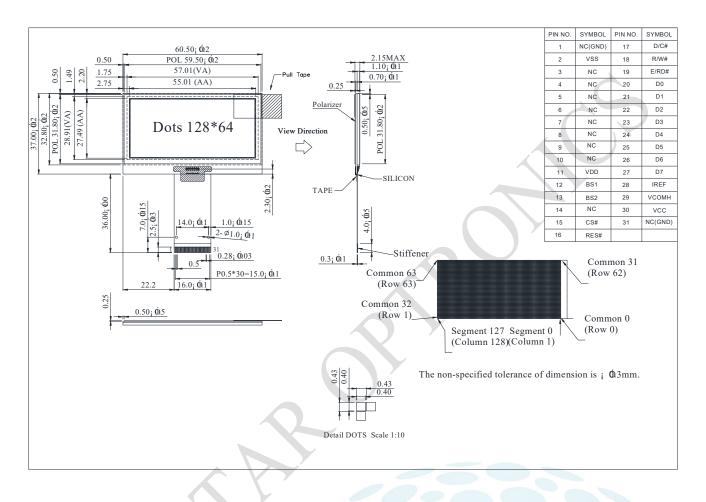
Pin No.	Symbol	Function				
1	NC(GND)	o connection (ground.)				
2	Vss	round pin. It must be connected to external ground.				
3~10	NC	No connection				
11	Vdd	Power supply pin for core logic operation				
12	BS1	MCU bus interface selection pins. Select appropriate logic setting as described in the				
		following table.				
		BS1 BS2				
		12C 1 0				
13	BS2	4-wire Serial 0 0				
	202	8-bit 68XX Parallel 0 1				
		8-bit 80XX Parallel 1 1				
		Note (1) 0 is connected to VSS (2) 1 is connected to VDD				
14	NC	No connection				
15	CS#	This pin is the chip select input connecting to the MCU. The chip is enabled for MCU communication only when CS# is pulled LOW (active LOW).				
16	RES#	This pin is reset signal input. When the pin is pulled LOW, initialization of the chip is executed. Keep this pin pull HIGH during normal operation.				
17	D/C#	This pin is Data/Command control pin connecting to the MCU. When the pin is pulled HIGH, the data at D[7:0] will be interpreted as data. When the pin is pulled LOW, the data at D[7:0] will be transferred to a command register. In I2C mode, this pin acts as SA0 for slave address selection. When 3-wire serial interface is selected, this pin must be connected to VSS. For detail relationship to MCU interface signals, refer to Timing				
		Characteristics				



interface. When 6800 interface mode is selected, this pin will be used as Read/Write (R/W#) selection input. Read mode will be carried out when this pin is pulled HIGH and write mode when LOW.			-
When 6800 interface mode is selected, this pin will be used as Read/Write (R/W#) selection input. Read mode will be carried out when this pin is pulled HIGH and write mode when LOW. When 8080 interface mode is selected, this pin will be the Write (WR#) input. Data write operation is initiated when this pin is pulled LOW and the chip is selected. When serial or I2C interface is selected, this pin must be connected to VSS. This pin is MCU interface input. When 6800 interface mode is selected, this pin will be used as the Enable (E) signal. Read/write operation is initiated when this pin is pulled HIGH and the chip is selected. When 8080 interface mode is selected, this pin receives the Read (RD#) signal. Read operation is initiated when this pin is pulled LOW and the chip is selected. When serial or I2C interface is selected, this pin must be connected to VSS. These pins are bi-directional data bus connecting to the MCU data bus. Unused pins are recommended to tie LOW. When serial interface mode is selected, D0 will be the serial clock input: SCLK; D1 will be the serial data input: SDIN and D2 should be kept NC. When I2C mode is selected, D2, D1 should be tied together and serve as SDAout, SDAin in application and D0 is the serial clock input, SCL. This pin is the segment output current reference pin. IREF is supplied externally. IREF A resistor should be connected between this pin and VSS to maintain the current around 10uA. Please refer to Figure 8-15 for the details of resistor value VCOMH A capacitor should be connected between this pin and VSS. Power supply for panel driving voltage. This is also the most positive power voltage supply pin.			This pin is read / write control input pin connecting to the MCU interface
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D0~D7 input: SCLK; D1 will be the serial data input: SDIN and D2 should be kept NC. When I2C mode is selected, D2, D1 should be tied together and serve as SDAout, SDAin in application and D0 is the serial clock input, SCL. This pin is the segment output current reference pin. IREF is supplied externally. A resistor should be connected between this pin and VSS to maintain the current around 10uA. Please refer to Figure 8-15 for the details of resistor value COM signal deselected voltage level. A capacitor should be connected between this pin and VSS. Power supply for panel driving voltage. This is also the most positive power voltage supply pin.			·
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28 IREF A resistor should be connected between this pin and VSS to maintain the current around 10uA. Please refer to Figure 8-15 for the details of resistor value 29 VCOMH COM signal deselected voltage level. A capacitor should be connected between this pin and VSS. 30 VCC Power supply for panel driving voltage. This is also the most positive power voltage supply pin.			
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resistor value 29 VCOMH COM signal deselected voltage level. A capacitor should be connected between this pin and VSS. Power supply for panel driving voltage. This is also the most positive power voltage supply pin.	20	IKEF	
A capacitor should be connected between this pin and VSS. Power supply for panel driving voltage. This is also the most positive power voltage supply pin.		M	
Power supply for panel driving voltage. This is also the most positive power voltage supply pin.	29	VCOMH	
power voltage supply pin.		. CONTI	
NC(GND) No connection (ground.)	30	VCC	
	31	NC(GND)	No connection (ground.)

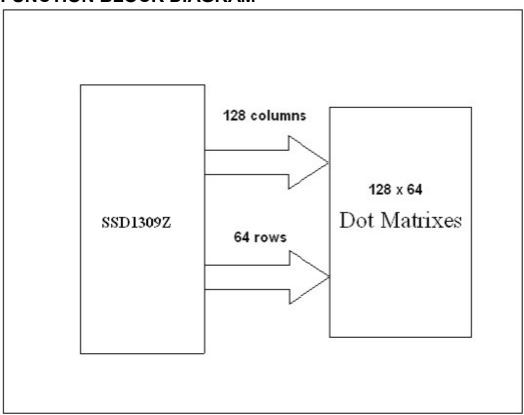


4. Counter Drawing & Block Diagram





FUNCTION BLOCK DIAGRAM



^{*}For more information, please refer to Application Note provided by Raystar Optronics.



5.Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit	Notes
Supply Voltage for Logic	VDD	-0.3	4	V	1, 2
Supply Voltage for Display	VCC	0	15	V	1, 2
Operating Temperature	TOP	-40	+80	°C	-
Storage Temperature	TSTG	-40	+80	°C	-

Note 1: All the above voltages are on the basis of "VSS = 0V".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 6 "Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate



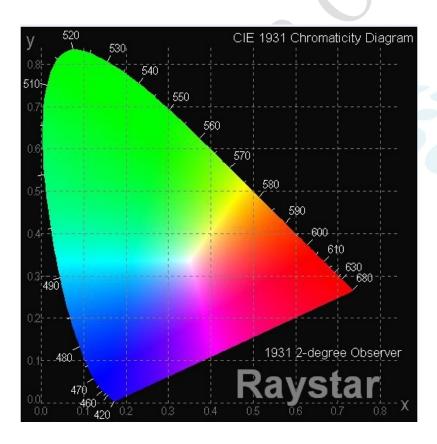
6.Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage for Logic	VDD	-	2.8	3.0	3.3	V
Supply Voltage for Display	VCC	-	12	13	15	V
High Level Input	VIH	-	0.8×VDD	-	VDD	V
Low Level Input	VIL	-	0		0.2×VDD	V
High Level Output	VOH	-	0.9×VDD	-	VDD	V
Low Level Output	VOL	-	0	-	0.1×VDD	V
50% Check Board operatir Current	ng	VCC =13V	15	18	22	mA



7. Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	(V)θ	-	160	-	7	deg
view, uigie	(Η)φ	-	160	- (deg
Contrast Ratio	CR	Dark	2000:1			-
Response Time	T rise	-	-	10	-	μs
Treepende Time	T fall	-		10	-	μs
Display with 50% check	Board Brig	htness	70	90	-	cd/m2
CIEx(Yellow)		(CIE1931)	0.45	0.47	0.49	-
CIEy(Yellow)		(CIE1931)	0.48	0.50	0.52	-



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8.OLED Lifetime

ITEM	Conditions	Min	Тур	Remark
Operating Life Time	Ta=25°C / Initial 50% check board brightness Typical Value	50,000 Hrs	-	Note

Notes:

- 1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.
- 2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.

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3. Screen saving mode will extend OLED lifetime.





9.Reliability

Content of Reliability Test

Environmenta	Il Test	T	IA P LI
Test Item	Content of Test	Test Condition	Applicable Standard
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80□ 240hrs	-, C
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-40 □ 240hrs	-
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	80□ 240hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-40 □ 240hrs	_
High Temperature/ Humidity Storage	Endurance test applying the high temperature and high humidity storage for a long time.	60□,90%RH 240hrs	
Temperature Cycle	Endurance test applying the low and high temperature cycle. -40 25 80 30min 5min 30min 1 cycle	-40□/80□ 100 cycles	
Mechanical Te	st		
Vibration test	Endurance test applying the vibration during transportation and using.	10~22Hz→1.5mmp-p 22~500Hz→1.5G Total 0.5hr	
Shock test	Constructional and mechanical endurance test applying the shock during transportation.	50G Half sin wave 11 ms 3 times of each direction	
Atmospheric pressure test	Endurance test applying the atmospheric pressure during transportation by air.	115mbar 40hrs	
Others			
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330Ω CS=150pF 10 times	1668

^{***} Supply voltage for OLED system =Operating voltage at 25°C



Test and measurement conditions

- 1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.
- 2. All-pixels-on is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

Evaluation criteria

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: > 50% of initial value.
- 4. Current consumption: within ± 50% of initial value.

APPENDIX:

RESIDUE IMAGE

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.



10.Inspection specification

NO	Item	Criterion					AQL
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 					0.65
02	Black or white spots on OLED (display only)	 2.1 White and black spots on display □0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm. 			2.5		
03	OLED black spots,	3.1 Round type following drawing Φ=(x + y) / 2		~	SIZE	Acceptable Q TY	
	white spots,				Ф≦0.10	Accept no dense	2.5
	contamina tion				0.10 < Φ≦0.20 2		
	(non-displ				0.20 < Φ≦0.2	5 1	
	ay)				0.25 < Ф	0	
		3.2 Line type : (A	As followin				
			Length	Wi	dth	Acceptable Q TY	2
	A			W	≦0.02	Accept no dense	
			L≦3.0	0.0)2 < W≦0.03	2	2.5
		7	L≦2.5	0.0	03 < W≦0.05		
				0.0)5 < W	As round type	
04	Polarizer						
	bubbles	judge using black spot specifications, not easy to find, must check in		—	ze Φ	Acceptable Q TY	
				Ф	≦0.20	Accept no dense	2.5
				0.2	20 < Φ≦0.50	3	
		specify direction		0.5	50 < Φ≦1.00	2	
				1.0)0 < Ф	0 /000	
			То	tal Q TY	3		



NO	Item	Criterion			AQL
05	Scratches	Follow NO.3 OLED b	lack spots, white spo	ts, contamination	
			t: Glass thickness a gth:	Chip thickness : OLED side length	
			surface and crack bet	ween panels:	
		z: Chip thickness	y: Chip width	x: Chip length	
	Ohim n a d	Z≦1/2t	Not over viewing area	x≦1/8a	
06	Chipped glass	1/2t < z≦2t	Not exceed 1/3k	x≦1/8a	2.5
		⊙If there are 2 or mo 6.1.2 Corner crack:	re chips, x is total len	gth of each chip.	
		z: Chip thickness	y: Chip width	x: Chip length	
		Z≦1/2t	Not over viewing area	x≦1/8a	
	7 (1/2t < z≦2t	Not exceed 1/3k	x≦1/8a	
		⊙If there are 2 or mo	re chips, x is the total	length of each chip.	







NO	Item	Criterion			AQL
		Symbols :			
			•	: Chip thickness	
			: Glass thickness	a: OLED side ler	igth
		L: Electrode pad leng 6.2 Protrusion over te			
		6.2.1 Chip on electron			
		0.2.1 Omp on oloon of	ao paa .		45
		011 111			
		y: Chip width	x: Chip length	z: Chip thickn	ess
		y≦0.5mm	x≦1/8a	0 < z ≦ t	
		6.2.2 Non-conductive	portion:		
				y	
	Class			_	
06	Glass crack				2.5
	ordon				
		y: Chip width	x: Chip length	z: Chip	
), op	w comprising	thickness	
		y≦ L	x≦1/8a	0 < z≦t	
					f the ITO
		⊙If the chipped area			
		must remain and be specifications.	e inspected accord	ng to electrode te	erminai
		olf the product will be	hoat soaled by the	o customer the a	lianment
				customer, the a	iigiiiileiit
		mark not be damag 6.2.3 Substrate protu		al crack	
		0.2.0 Gabotrato prota			
			y: width	x: length	
			y≦1/3L	x≦a	
					4000
					12000000
				4	1000







NO	Item	Criterion	AQL
07	Cracked glass	The OLED with extensive crack is not acceptable.	2.5
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB、COB	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or screw hold pad, make sure it is smoothed down. 	2.5 2.5 0.65 2.5 2.5 0.65 2.5
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65



12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 OLED pin loose or missing pins. 12.10 Product packaging must the same as specified on packaging specification sheet. 12.11 Product dimension and structure must conform to	NO	Item	Criterion	AQL
product specification, sheet.	12		 interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 OLED pin loose or missing pins. 12.10 Product packaging must the same as specified on packaging specification sheet. 	2.5 0.65 2.5 2.5 2.5 2.5 0.65 0.65 0.65



Check Item	Classification	Criteria
No Display	Major	
Missing Line	Major	
Pixel Short	Major	
Darker Short	Major	
Wrong Display	Major	
Un-uniform B/A x 100% < 70% A/C x 100% < 70%	Major	
		A Normal B Dark Pixel C Light Pixel



11.Precautions in use of OLED Modules

- (1) Avoid applying excessive shocks to module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, modify its shape or change the components of OLED display module.
- (3) Don't disassemble the OLED display module.
- (4) Don't operate it above the absolute maximum rating.
- (5) Don't drop, bend or twist OLED display module.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) It's pretty common to use "Screen Saver" to extend the lifetime and Don't use fix information for long time in real application.
- (9) Don't use fixed information in OLED panel for long time, that will extend "screen burn" effect time..
- (10) Raystar has the right to change the passive components, including R2and R3 adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (11) Raystar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Raystar have the right to modify the version.)

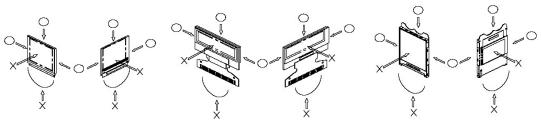
11.1 Handling Precautions

- (1) Since the display panel is being made of glass, do not apply mechanical impacts such us dropping from a high position.
- (2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- (3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged and be careful not to apply pressure to these sections.
- (4) The polarizer covering the surface of the OLED display module is soft and easily scratched. Please be careful when handling the OLED display module.
- (5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage of by using following adhesion tape.
- * Scotch Mending Tape No. 810 or an equivalent

Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent Also, pay attention that the following liquid and solvent may spoil the polarizer:

- * Water
- * Ketone
- * Aromatic Solvents
- (6) Hold OLED display module very carefully when placing OLED display module into the System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.





- (7) Do not apply stress to the LSI chips and the surrounding molded sections.
- (8) Do not disassemble nor modify the OLED display module.
- (9) Do not apply input signals while the logic power is off.
- (10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
- * Be sure to make human body grounding when handling OLED display modules.
- * Be sure to ground tools to use or assembly such as soldering irons.
- * To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
- * Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.
- (11) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
- (12) If electric current is applied when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above.

11.2 Storage Precautions

- (1) When storing OLED display modules, put them in static electricity preventive bags avoiding exposure to direct sun light nor to lights of fluorescent lamps. And, also, avoiding high temperature and high humidity environment or low temperature (less than 0°C) environments. (We recommend you to store these modules in the packaged state when they were shipped from Raystar Optronics Inc. At that time, be careful not to let water drops adhere to the packages or bags nor let dewing occur with them.
- (2) If electric current is applied when water drops are adhering to the surface of the OLED display module, when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful about the above.





11.3 Designing Precautions

- (1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, panel damage may be happen.
- (2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specifications and, at the same time, to make the signal line cable as short as possible.
- (3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD). (Recommend value: 0.5A)
- (4) Pay sufficient attention to avoid occurrence of mutual noise interference with the neighboring devices.
- (5) As for EMI, take necessary measures on the equipment side basically.
- (6) When fastening the OLED display module, fasten the external plastic housing section.
- (7) If power supply to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module. Connection (contact) to any other potential than the above may lead to rupture of the IC.



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Module Sample Estimate Feedback Sheet					
Module Number :					
1、Panel Specification:					
1. Panel Type :	□ Pass	□NG ,			
2. Numbers of Pixel:	□ Pass	□NG ,			
3. View Area :	□ Pass	□NG ,			
4. Active Area:	□ Pass	□NG ,			
5.Emitting Color:	□ Pass	□NG ,			
6.Uniformity:	□Pass	□NG ,			
7.Operating Temperature :	□ Pass	□NG ,			
8.Storage Temperature :	□ Pass	□NG ,			
9.Others :					
2、 Mechanical Specification :					
1. PCB Size :	□Pass	□NG ,			
2.Frame Size :	□Pass	□NG ,			
3.Materal of Frame :	□Pass	□NG ,			
4.Connector Position:	□Pass	□NG ,			
5.Fix Hole Position:	□Pass	□NG ,			
6. Thickness of PCB:	□Pass	□NG ,			
7. Height of Frame to PCB:	□Pass	□NG ,			
8.Height of Module:	□Pass	□NG ,			
9.Others:	□Pass	□NG ,			
3、Relative Hole Size:					
1.Pitch of Connector :	□Pass	□NG ,			
2.Hole size of	□Pass	□NG ,			
Connector :		16000000			
3.Mounting Hole size:	□Pass	□NG ,			
4.Mounting Hole Type:	□Pass	□NG ,			



5.Others:	□Pass	□NG ,
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Page: 2 Module Number : _ 4、 Electronic Characteristics of Module : □NG ,___ □Pass 1.Input Voltage: □Pass □NG ,___ 2. Supply Current: □NG ,_____ 3.Driving Voltage for □Pass OLED: □Pass □NG ,___ 4.Contrast for OLED: □NG ,___ 5.Negative Voltage □Pass Output: □NG ,___ □Pass 6.Interface Function: □NG ,___ □Pass 7.ESD test: □NG ,___ □Pass 8.Others: 5. Summary: Sales signature : Date:

Customer Signature : _____



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